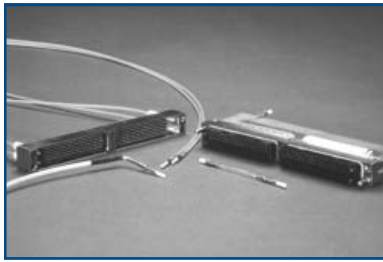


Rectangular Printed Circuit Board Interconnects, cont.

LRM Surface Mount Connectors with Fiber Optics, RF Modules, Power Supply Modules

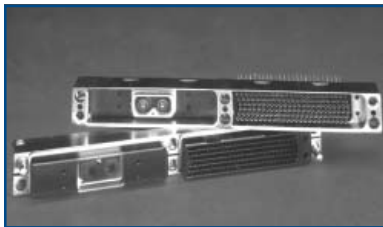
Reference L-2104 LRM Reference Guide



LRM with Fiber Optics



RF Modules



Power Supply Modules

APPLICATION	STANDARDS/ REQUIREMENTS	COUPLING/ MOUNTING	CONTACT TERMINATION/ ARRANGEMENTS	PERFORMANCE ENVIRON./ELECT.
Line replaceable modular interconnects with very high contact densities, for attachment to printed circuit boards. Offers versatility of combining contact types within modules - fiber optics, shielded RF coax, and power contacts one high density package.	High performance LRM connectors with hybrid contact arrangements available.	Same as for LRM connectors shown on preceding page.	Combinations of: <ul style="list-style-type: none"> • Brush contacts • Fiber Optic LRM - MIL-T-29504 type termini or MT ferrules (2-24 fiber lines per ferrule) • RF Modules with coax contacts - size 16 M39029 type, size 12 for DC-2 GHz or size 8 for DC-32 GHz. Other RF contacts can be accommodated. • Power Supply Modules with custom 270VDC sections utilizing size 22D crimp or compliant pin contacts. Crimp termination size 16, 12 and 8 contacts for high current applications. 	Connector performances and brush contact performances are the same as shown on preceding page for LRM connectors. Power supply modules with 270VDC sections are capable of providing corona-free operation at 75,000 ft.

OPTIONAL FEATURES

- Digital/Brush contact inserts can be partially populated to permit high voltage carrying capacity through the electrical PWB, while isolating sensitive electrical signals.
- Differential pair inserts have been specifically designed to support data rates with excess of 1.2 Gbps.
- Also see page 40 for optical backplane interconnection system, that can provide up to 192 fiber optic lines and 80 digital contacts in SEM-E format.

MARKETS

- Military and Commercial Aviation
- Military Vehicles
- GPS Systems

Thermal Clamps

Consult your local Amphenol sales office for further information.



APPLICATION	STANDARDS/ REQUIREMENTS	COUPLING/ MOUNTING	CONTACT TERMINATION/ ARRANGEMENTS	PERFORMANCE ENVIRON./ELECT.
For attachment to printed circuit boards to ensure the thermal dissipation of the PC board from the heatsinks to the chassis. Unique design produces a uniform pressure distribution, eliminating hot spots along the PCB edge.	Meets all performance objectives set by military and commercial users for high reliability and high density circuit board packaging of electronic equipments.	Provides for quick, positive guiding and locking of the daughter boards into the correct position (simply through a 1/4 turn). Visual indication that shows the "open" and "closed" position.	Fits to the PC board as required. Board lengths between 40 mm (1.57 in.) and 300 mm (11.81 in.) can be accommodated once the cold wall and heat sink are specified. Compatible with different heat sinks thicknesses. Various mounting, locking devices are available.	Operating temp. range: 1000 hours @ 125° C. The assembly of body, spring system, and axis has no moving parts and permits the clamp to stay together even when in unlocked position. Provides space saving, low weight and zero insertion/extraction forces. Very low wear and resistance to shocks and vibration, even in harsh environments. Springs are copper beryllium. Body is aluminum and axis is stainless steel.

OPTIONAL FEATURES

- Available in the following configurations:
 - with shell to be fixed on the structure
 - without shell to be fixed on the structure (machining drawing available)
 - without shell to be fixed directly on the heatsink
- Designed per customer requirements for lengths, plating options, and other design variations.

MARKETS

- Radar Equipment and Weapons Systems
- High Speed Calculators
- Submarine Equipment
- Ground Military Vehicles